

Power Management ICs for Automotive Body Control

# Regulator with Voltage Detector and Watchdog Timer



BD3010AFV-M

No.10039EAT09

## ●Description

BD3010AFV-M is a regulator IC with integrated WDT (Watch Dog Timer), high output voltage accuracy  $\pm 2.0\%$  and  $80\mu\text{A}$  (Typ.) low circuit current consumption. BD3010AFV-M supports usage of low ESR ceramic capacitor for output stability. Also integrated is an automatic WDT ON/OFF feature using output current detection and an output clamping circuit to prevent output overshoot caused by current flow. The reset detection voltage can be adjusted by connecting resistors on the RADI terminal. BD3010AFV-M can be a stable power supply for any applications while detecting malfunction of microcontrollers.

## ●Features

- 1) Vcc Max Voltage . . . 50V
  - 2) High Output Voltage Accuracy . . .  $\pm 2.0\%$  ( $T_a = -40 \sim 125^\circ\text{C}$ )
  - 3) Low Circuit Current . . .  $80\mu\text{A}$  (Typ.)
  - 4) Output Circuit . . . Pch DMOS
  - 5) Supports Low ESR Ceramic Capacitor
  - 6) Integrated Over Current Protection and Thermal Shut Down
  - 7) Integrated WDT Reset Circuit (Adjustable Detection Voltage through RADI pin)
  - 8) Integrated Automatic WDT ON/OFF Function through Output Current Detection
  - 9) WDT Can be Switched ON/OFF by Using INH Pin
  - 10) Integrated Output Voltage Clamping Circuit
- Package . . . SSOP-B20

## ●Applications

Any application using a microcontroller or a DSP such as automotive (body control), display, server, DVD, phone, etc

●Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Supply voltage <sup>*1</sup>	Vcc	-0.3 ~ +50	V
VADJ set pin voltage	VADJ	-0.3 ~ +7	V
Regulator output pin voltage	VOUT	-0.3 ~ +7	V
INH pin voltage	VINH	-0.3 ~ +15	V
Reset output pin voltage	VRo	-0.3 ~ +7	V
Watchdog input pin voltage	VCLK	-0.3 ~ +15	V
Watchdog time set pin voltage	VCT	-0.3 ~ +7	V
Watchdog operation current set pin voltage	VWADJ	-0.3 ~ +7	V
Power dissipation <sup>*2</sup>	Pd	1.25	W
Operating temperature range	Topr	-40 ~ +125	°C
Storage temperature range	Tstg	-55 ~ +150	°C
Maximum junction temperature	Tjmax	150	°C

\*1 Not to exceed Pd.

\*2 Reduced by 10.0mW/°C over Ta=25°C, when mounted on 70mm × 70mm × 1.6mm glass epoxy board:

●Operating Conditions(Ta=-40 ~ +125°C)

Parameter	Symbol	Min.	Max.	Unit
Supply Voltage <sup>*3</sup>	Vcc	5.6	36.0	V
Supply Voltage <sup>*4</sup>	Vcc	6.0	36.0	V
Output current	Io	0	200	mA

\*3 For the output voltage, consider the voltage drop (dropout voltage) due to the output current.

\*4 Operating condition for automatic WDT ON/OFF.

NOTE: This product is not designed for protection against radioactive rays.

**Electrical characteristics**(Unless otherwise specified, Ta=-40 ~ +125°C, Vcc=13.5V, INH=5V, CLK=GND, Io=0mA)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
[Entire Device]						
Circuit current 1	Icc1	—	80	140	μA	
Circuit current 2	Icc2	—	110	170	μA	Io=50mA(Ta=25°C)
[Regulator]						
Output voltage	OUT	4.90	5.00	5.10	V	
Line regulation	Line.Reg	—	5	30	mV	Vcc=5.6 ~ 36V
Load regulation	Load.Reg	—	20	60	mV	Io=5 ~ 150mA
Dropout voltage	ΔVd	—	0.25	0.50	V	Vcc=4.75V, Io=150mA
Ripple rejection	R.R.	45	55	—	dB	f=120Hz, ein=1Vrms, Io=100mA
WADJ mirror current ratio	ΔI	0.002	0.010	0.025	—	Io=50mA(output)
Output voltage clamp (Comparator)	Vclp	5.2	5.5	5.8	V	Io=20mA(input)
[Reset]						
Detection voltage	Vdet	4.12	4.25	4.38	V	RADJ=Open
Hysteresis width	VHS	35	70	150	mV	
Output delay time L→H (Power On Reset)	TdLH	1.8	2.3	2.8	ms	OUT=Vdet±0.5V, CT=0.01μF
Low output voltage	VRST	—	0.1	0.4	V	OUT=4.0V
Min. operating voltage	VOPL	1.5	—	—	V	
[Watchdog Timer]						
Upper switching threshold voltage	VthH	1.08	1.15	1.25	V	WDT ON, INH=Open
Lower switching threshold voltage	VthL	0.13	0.15	0.17	V	WDT ON, INH=Open
WDT charge current	Ictc	3.5	5.0	6.5	μA	WDT ON, INH=Open, CT=0V
WDT discharge current	Ictd	0.8	1.3	1.7	μA	WDT ON, INH=Open, CT=1.3V
WDT watch time	TWH	6.4	8.0	9.6	ms	WDT ON, INH=Open, CT=0.01μF(Ceramic Cap)
WDT reset time	TWL	1.6	2.0	2.4	ms	※Characteristics of ceramic cap not considered.
WDT operating current	IOA	0.3	1.7	4.0	mA	WDT ON, INH open, 5kΩ resistor is placed between WADJ and OUT pins. ※Characteristics of external resistor not considered.
[INH]						
WDT OFF threshold voltage	VHINH	OUT ×0.8	—	OUT	V	
WDT ON threshold voltage	VLINH	0	—	OUT ×0.3	V	Pulled down inside the IC when INH=open
INH input current	IINH	—	15	30	μA	INH=5V
[CLK]						
CLK OFF threshold voltage	VLCLK	0	—	OUT ×0.3	V	
CLK ON threshold voltage	VHCLK	OUT ×0.8	—	OUT	V	
CLK input pulse width	TWCLK	500	—	—	ns	

●Reference Data

(Unless otherwise specified, Ta=25°C, Vcc=13.5V, INH=5V, CLK=GND, Io=0mA)

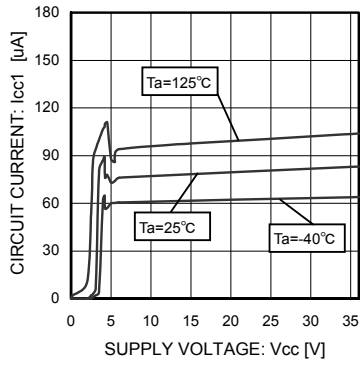


Fig.1 Circuit Current 1

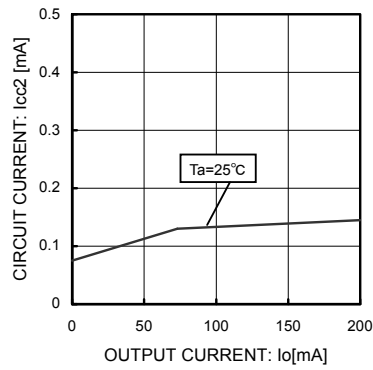


Fig.2 Circuit Current 2

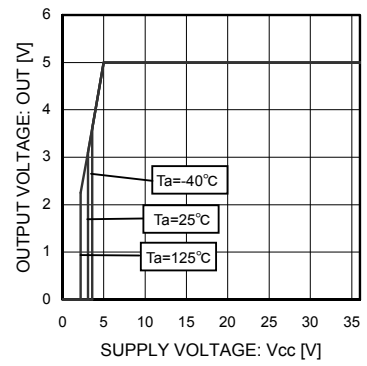


Fig.3 Input Stability

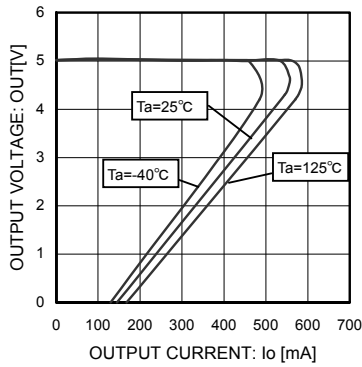


Fig.4 Load Stability

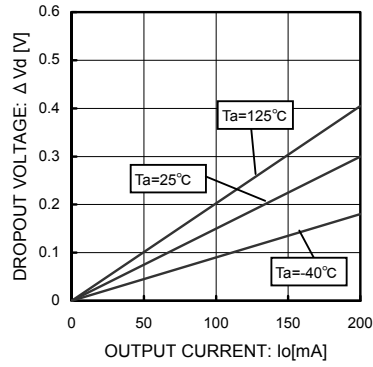


Fig.5 I/O Voltage Difference (Vcc=4.75V)

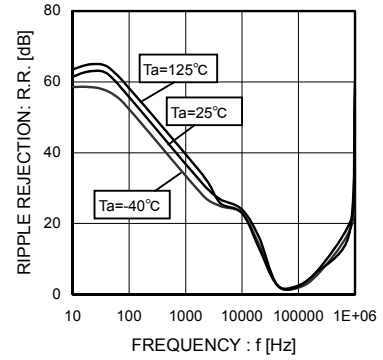


Fig.6 Ripple Rejection

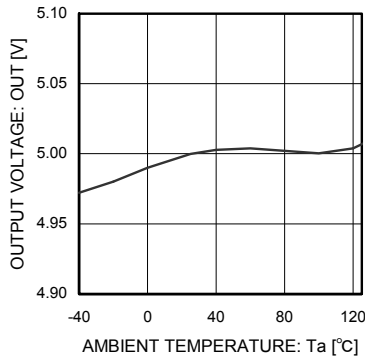


Fig.7 Output Voltage vs. Temperature

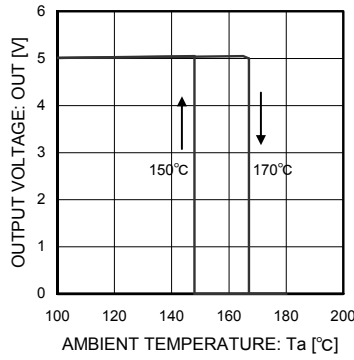


Fig.8 Thermal Shutdown Circuit Characteristics

●Reference Data

(Unless otherwise specified, Ta=25°C, Vcc=13.5V, INH=5V, CLK=GND, Io=0mA)

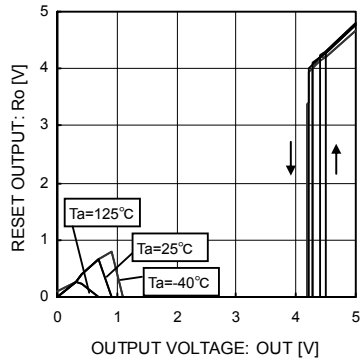


Fig.9 Voltage detection (RADJ=Open)

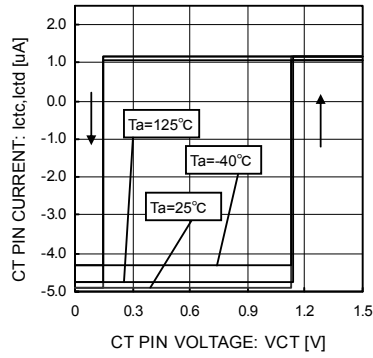


Fig.10 CT Pin Charge / Discharge Current (Vcc=5V)

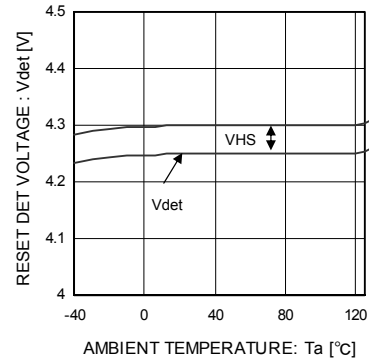


Fig.11 Reset Detection Voltage vs. Temperature

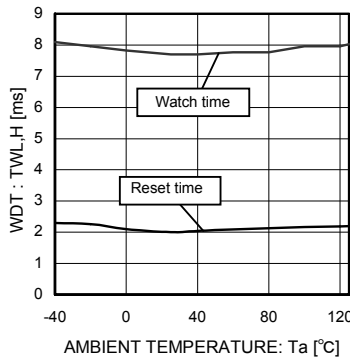


Fig.12 WDT Time vs. Temperature (CT=0.01μF) (Vcc=5V)

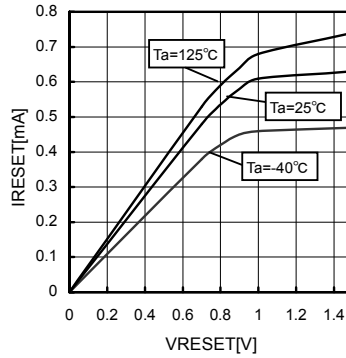


Fig.13 VRESET\_IRESET (OUT=1.5V, Ro=0.5V)

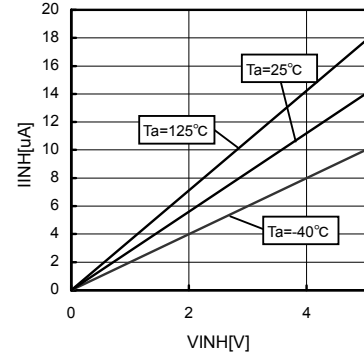


Fig.14 VINH\_IINH

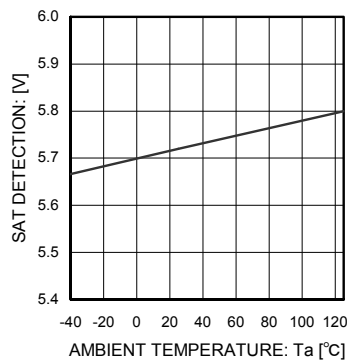


Fig.15 SAT detection vs. Temperature

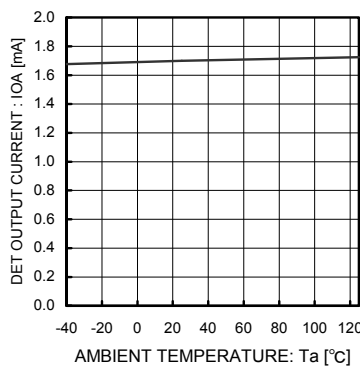


Fig.16 WDT Current Detection vs. Temperature (WADJ-OUT = 5kΩ)

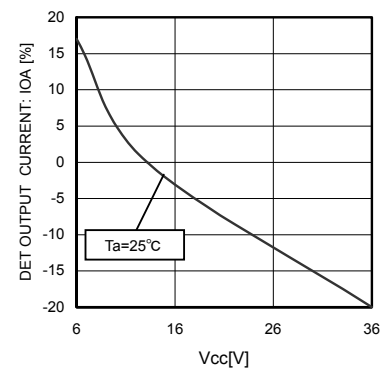
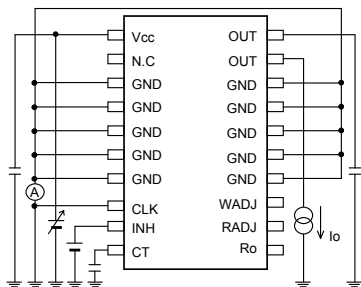
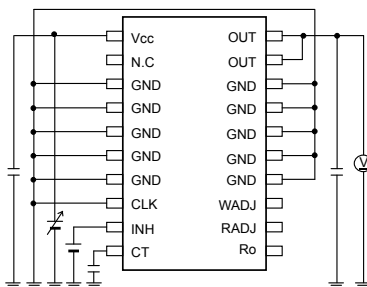


Fig.17 WDT Current Detection vs. Vcc (WADJ-OUT = 5kΩ)

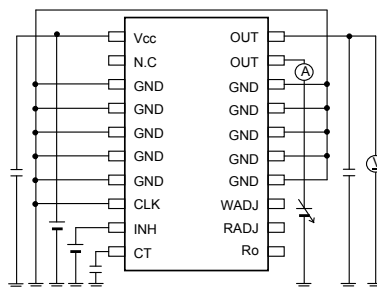
● Measurement Circuit for Electrical Data



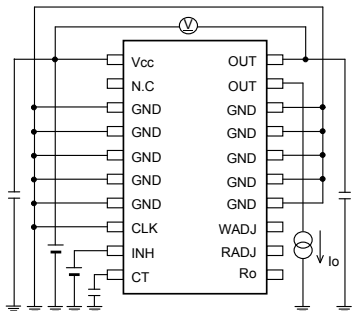
Measurement Circuit of Fig.1 and Fig.2



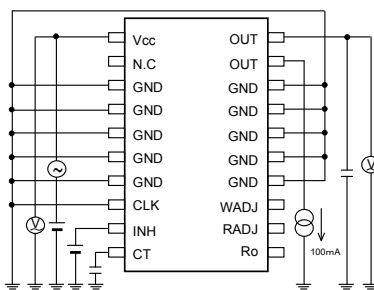
Measurement Circuit of Fig.3 and Fig.7 and Fig.8



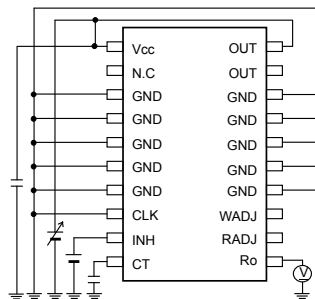
Measurement Circuit of Fig.4



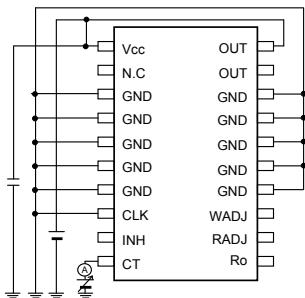
Measurement Circuit of Fig.5



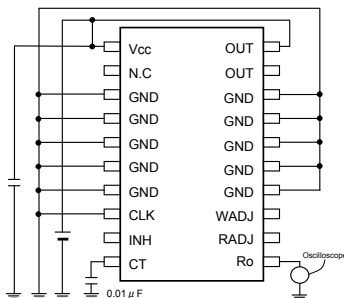
Measurement Circuit of Fig.6



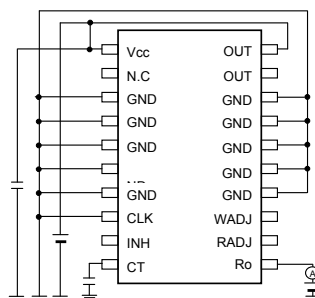
Measurement Circuit of Fig.9 and Fig.11



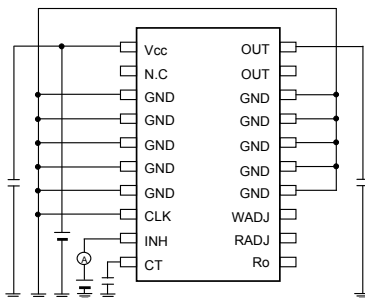
Measurement Circuit of Fig.10



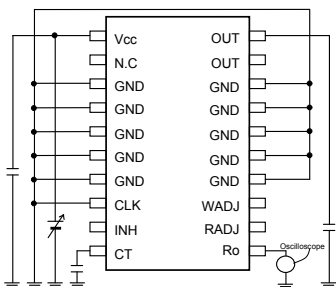
Measurement Circuit of Fig.12



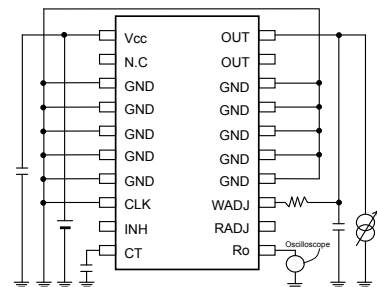
Measurement Circuit of Fig.13



Measurement Circuit of Fig.14



Measurement Circuit of Fig.15



Measurement Circuit of Fig.16 and Fig.17

●Block Diagram

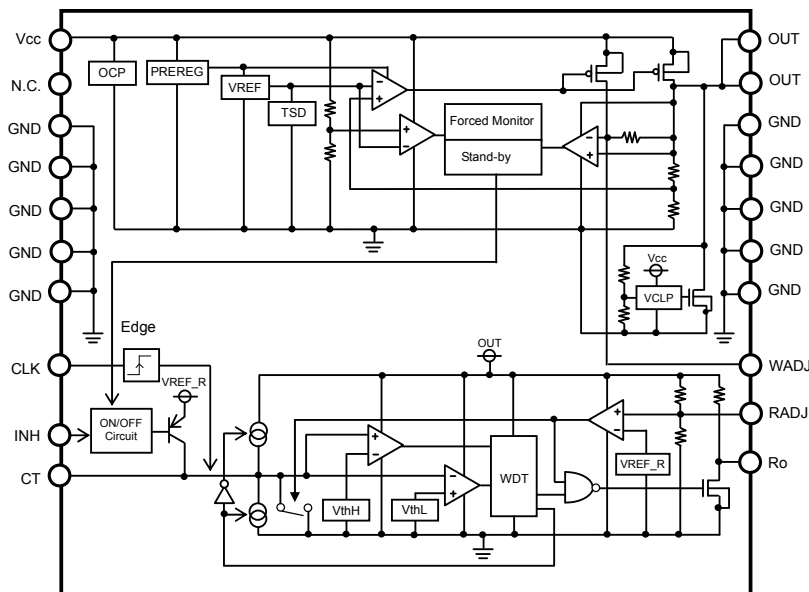
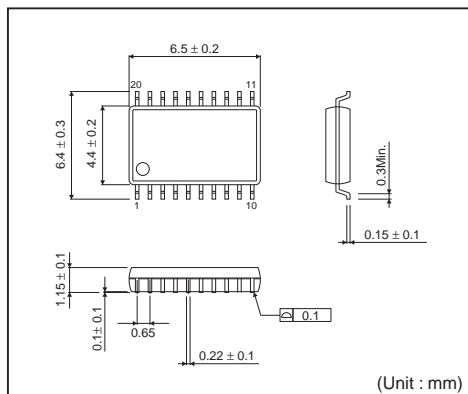


Fig.18

Pin No.	Pin Name	Function	Pin No.	Pin Name	Function	
1	Vcc	Power supply Pin	11	Ro	Reset output pin	
2	N.C.	—	12	RADJ	Reset detection voltage set pin	
3	GND	GND	13	WADJ	WDT operating current set pin	
4	GND		14	GND	GND	
5	GND		15	GND		
6	GND		16	GND		
7	GND		17	GND		
8	CLK	Clock input from microcontroller	18	GND	GND	
9	INH	WDT ON/OFF function pin	19	OUT		Voltage output pin
10	CT	External capacitance for reset output delay time, WDT monitor time setting connection pin	20	OUT		

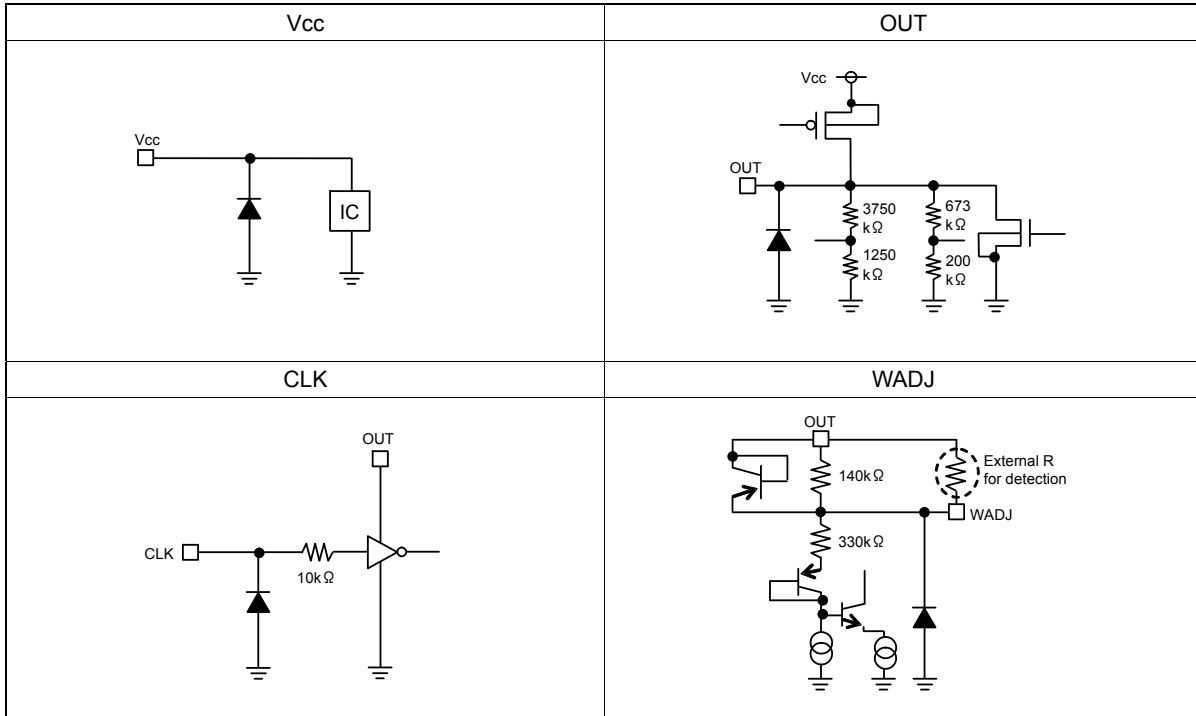
●Top View (Package dimension)



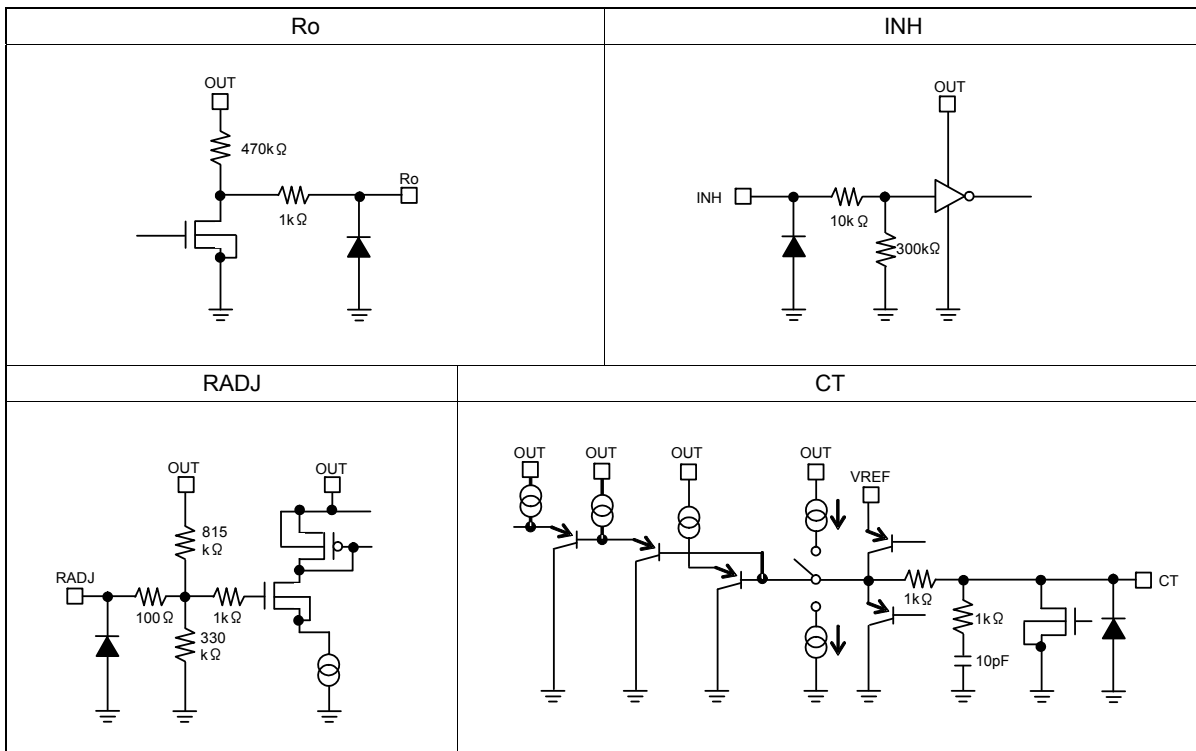
SSOP-B20

● I/O Equivalent Circuits (Resistance value is Typ. value)

<Regulator>

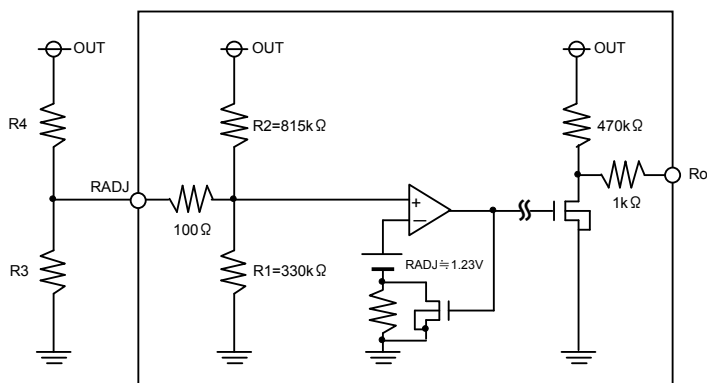


<Reset>





●Detection Voltage Adjustment (Resistance Value is TYP. value)



IC Internal Block Diagram

When typical detection voltage is 4.25V

$$V_{det} \cong RADJ \times (R1+R2) / R1$$

- $V_{det}$  : Reset detection voltage
- RADJ : Internal reference voltage (MOS input)
- R1,R2 : IC internal resistor (Voltage detection precision is tightened up to  $\pm 3\%$  by laser-trimming the R1 and R2)

RADJ will fluctuate  $1.23V \pm 6.0\%$

Insert pull down resistor R3 (lower resistance than R1) in between RADJ-GND, and pull down resistor R4 (lower resistance than R2) in between RADJ-OUT to adjust the detection voltage.

By doing so, the detection voltage can be adjusted by the calculation below.

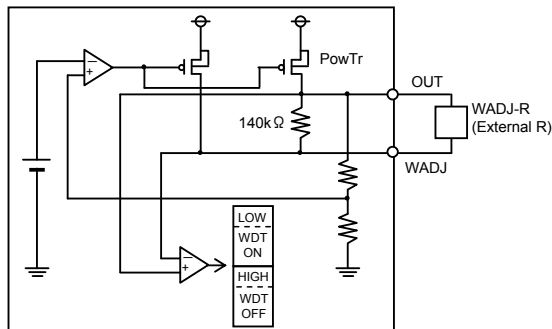
$$V_{det} = RADJ \times \left[ \frac{R2 \times R4}{R2+R4} + \frac{R1 \times R3}{R1+R3} \right] / \left[ \frac{R1 \times R3}{R1+R3} \right]$$

When the output resistance value is as small enough to ignore the IC internal resistance, you can find the detection voltage by the calculation below.

$$V_{det} \cong RADJ \times (R3+R4) / R3$$

Adjust the resistance value by application as the circuit current will increase due to the added resistor.

●WDT Voltage Detection (Resistance Value is TYP. value)



IC Internal Block Diagram

WDT can be automatically switched ON/OFF by the output load current. To detect the output load current, add a resistor between OUT-WADJ. Current detection is adjustable by selecting 1 kΩ ~ 15kΩ resistance.

Calculation:

$$I_O(\text{Desired load current value}) \times \Delta I(\text{WADJ current mirror ratio}) \times (\text{external } R / 140k\Omega)^{\ast 1} \geq 100mV^{\ast 2}$$

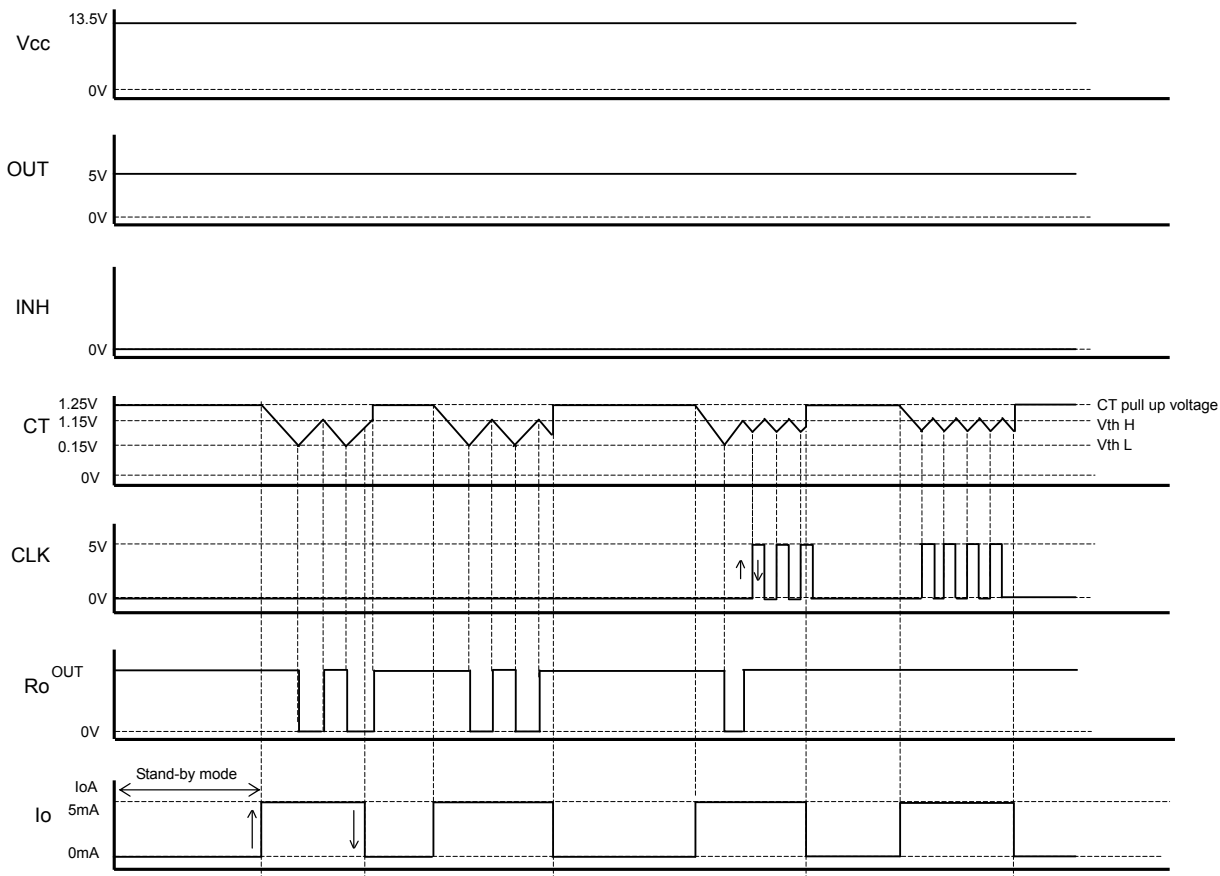
- ※1 is IC internal resistance between WADJ-OUT (tolerance approx ±30%, temperature coefficient approx 2000ppm)
- ※2 is an offset of detection comparator (tolerance approx 100mV±10%)

When there is no resistance between WADJ-OUT,  $I_O=70\mu A$  can be detected by the calculation below

$$I_O(\text{Desired load current value}) \times \Delta I(\text{WADJ current mirror ratio}) \times 140k\Omega \geq 100mV$$

※If the OUT-WADJ resistance value is not same as the condition on the electrical characteristics table, i.e., 5KΩ, choose the resistance value in ratio referring to the above equation.

<Timing Chart> Timing Chart from the no load condition (Stand-by Mode)



●Power ON Reset

Power ON reset (output delay time) is adjustable by CT pin capacitor.

$$T_{dLH}(S) \cong (1.15V \times CT \text{ capacitance}(\mu F) / I_{ctc}(\mu A)(TYP.))$$

- TdLH : Output delay time( power ON reset)
- 1.15V : Upper switching threshold voltage(TYP.)
- CT capacitance : Capacitor connected to CT pin
- Ictc : WDT charge current

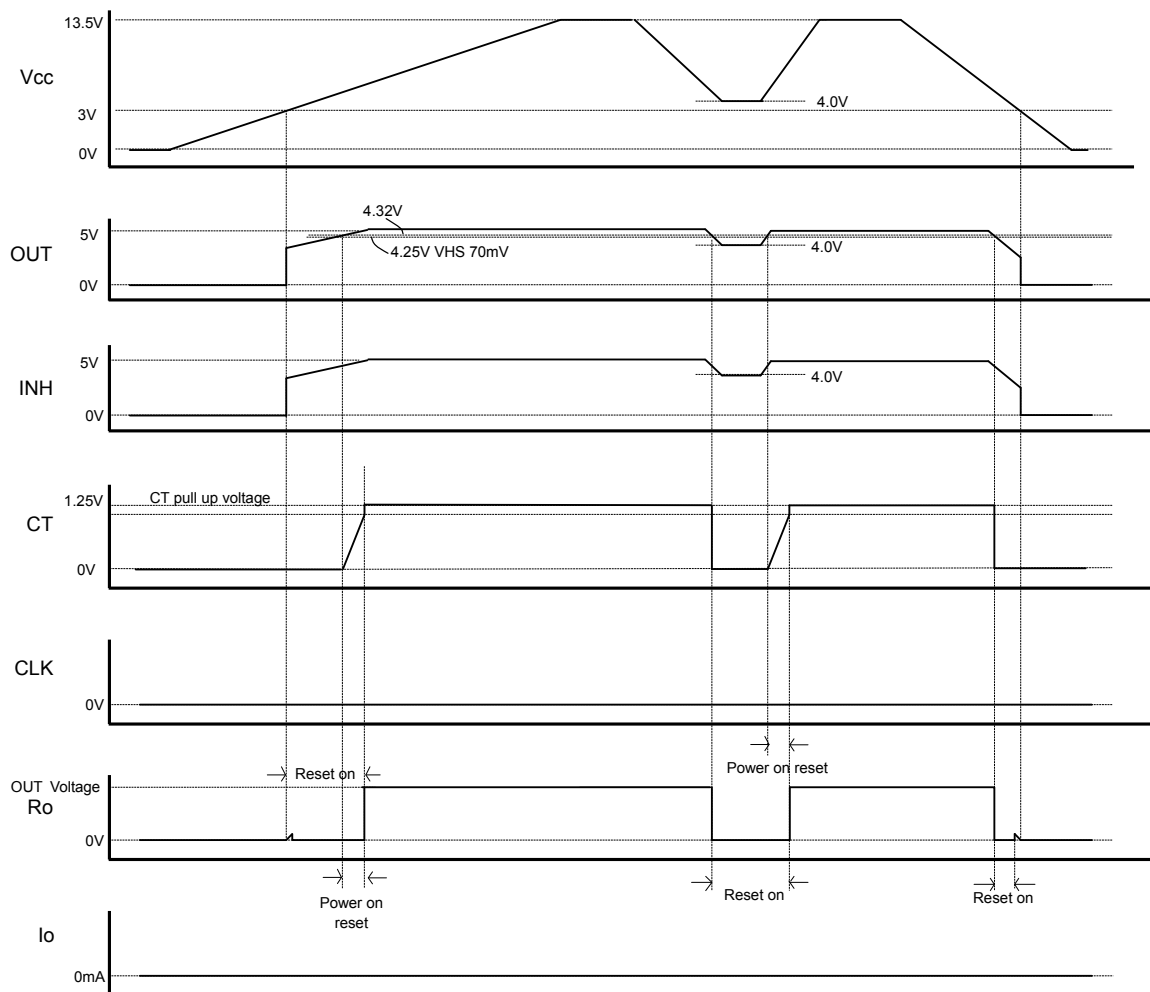
<Calculation example>with 0.01μF CT pin capacitor

$$T_{dLH}(S) = 1.15V \times 0.01\mu F / 5.0\mu A$$

$$\cong 2.3msec$$

※If the CT capacitance is not the same as the condition on the electrical characteristics table, i.e., 0.01μF, choose the capacitance value in ratio referring to the above equation.

<Timing Chart> ※Watchdog Timer OFF(INH ON)



● Watchdog Timer

Watch Dog Timer ( WDT watch time, reset time) is adjustable by the CT pin capacitor

$$TWH(S) \cong (1.00V \times CT \text{ capacitance } (\mu F)) / Ictd(\mu A) \quad (\text{Typ.})$$

$$TWL(S) \cong (1.00V \times CT \text{ capacitance } (\mu F)) / Ictc(\mu A) \quad (\text{Typ.})$$

- TWH : WDT watch time (delay time to turn the reset ON)
- TWL : WDT reset time (time the reset is ON)
- 1.00V : Upper switching threshold voltage - lower switching threshold voltage
- CT capacitance : CT pin capacitor ※Shared with power ON reset
- Ictc : WDT charge current
- Ictd : WDT discharge current

※WDT time's accuracy is ±20% by trimming

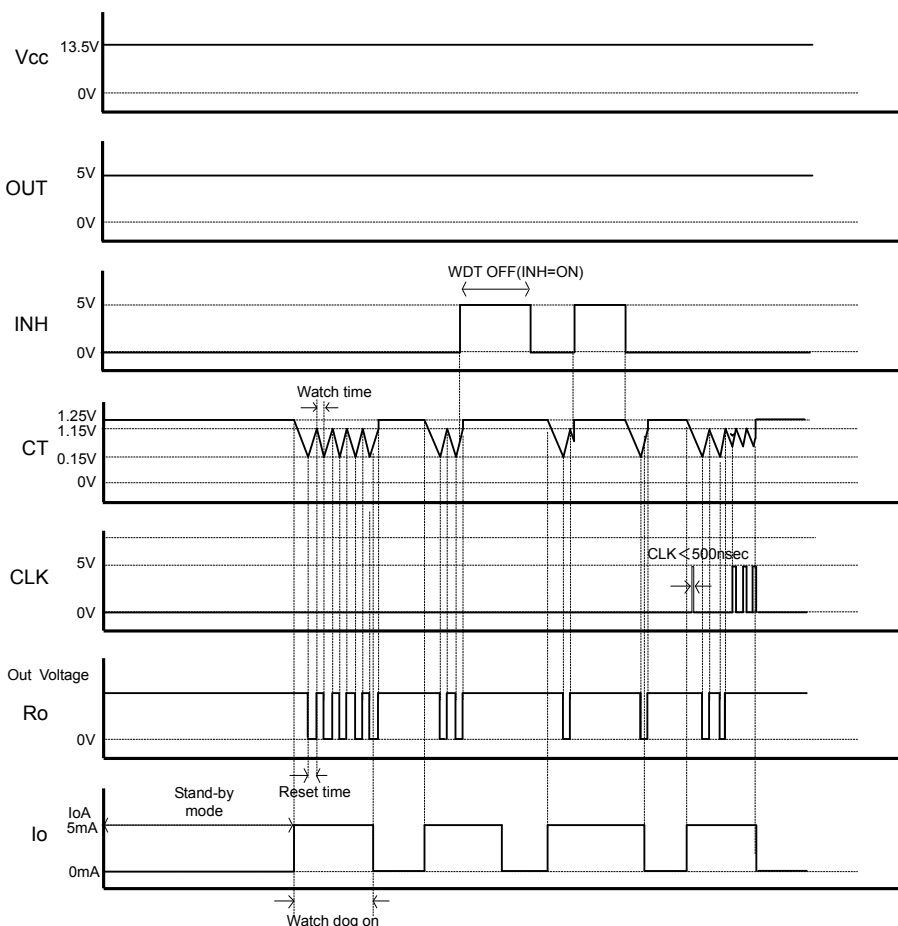
<Calculation example> with 0.01μF CT pin capacitor

$$TWH(S) \cong 1.00V \times 0.01\mu F / 1.3\mu A \cong 8.0\text{msec} \quad (\text{Typ.})$$

$$TWL(S) \cong 1.00V \times 0.01\mu F / 5.0\mu A \cong 2.0\text{msec} \quad (\text{Typ.})$$

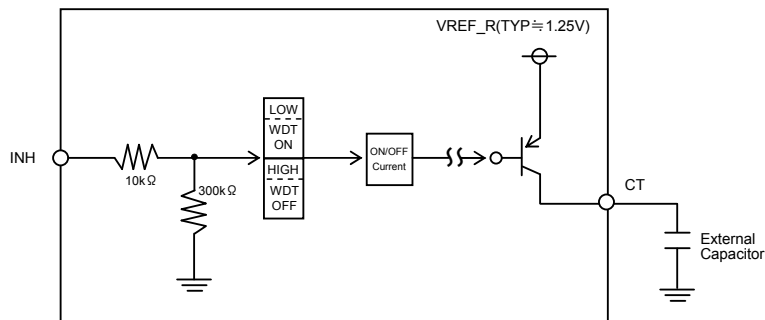
※If the CT capacitance is not the same as the condition on the electrical characteristics table, choose the capacitance value in ratio referring to the above equation.

<Timing Chart>



●WDT timer ON/OFF switch INH (Resistance value is Typ. value)

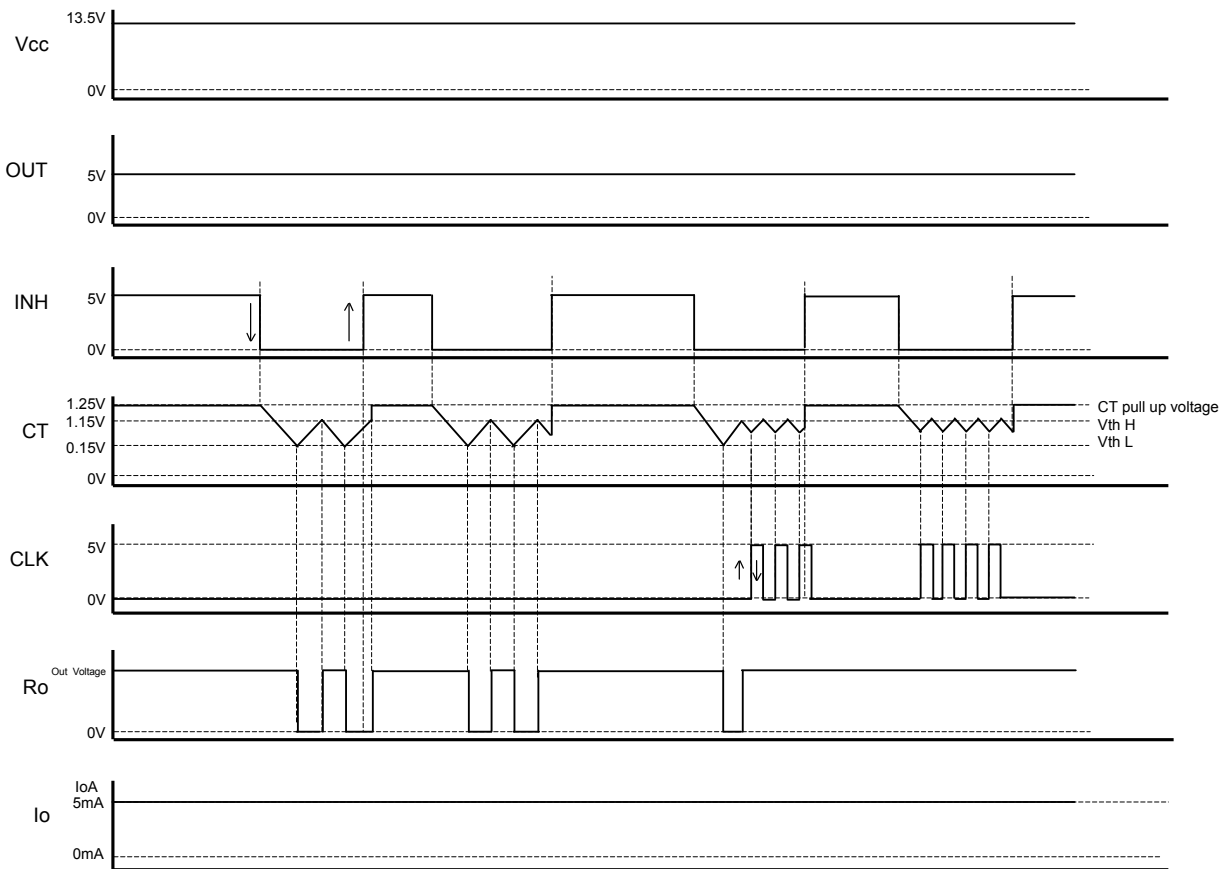
BD3010AFV-M has a switch INH to turn the WDT ON/OFF



IC Internal Block Diagram

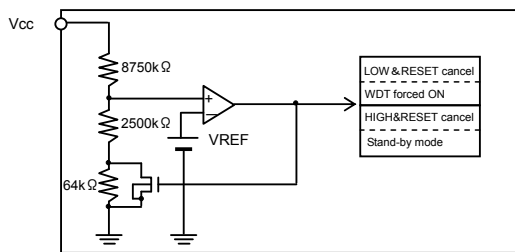
By using INH ON, CT potential can be pulled up to internal voltage VREF\_R (invalid with power ON reset)

<Timing Chart>



● Forced Watch Mode

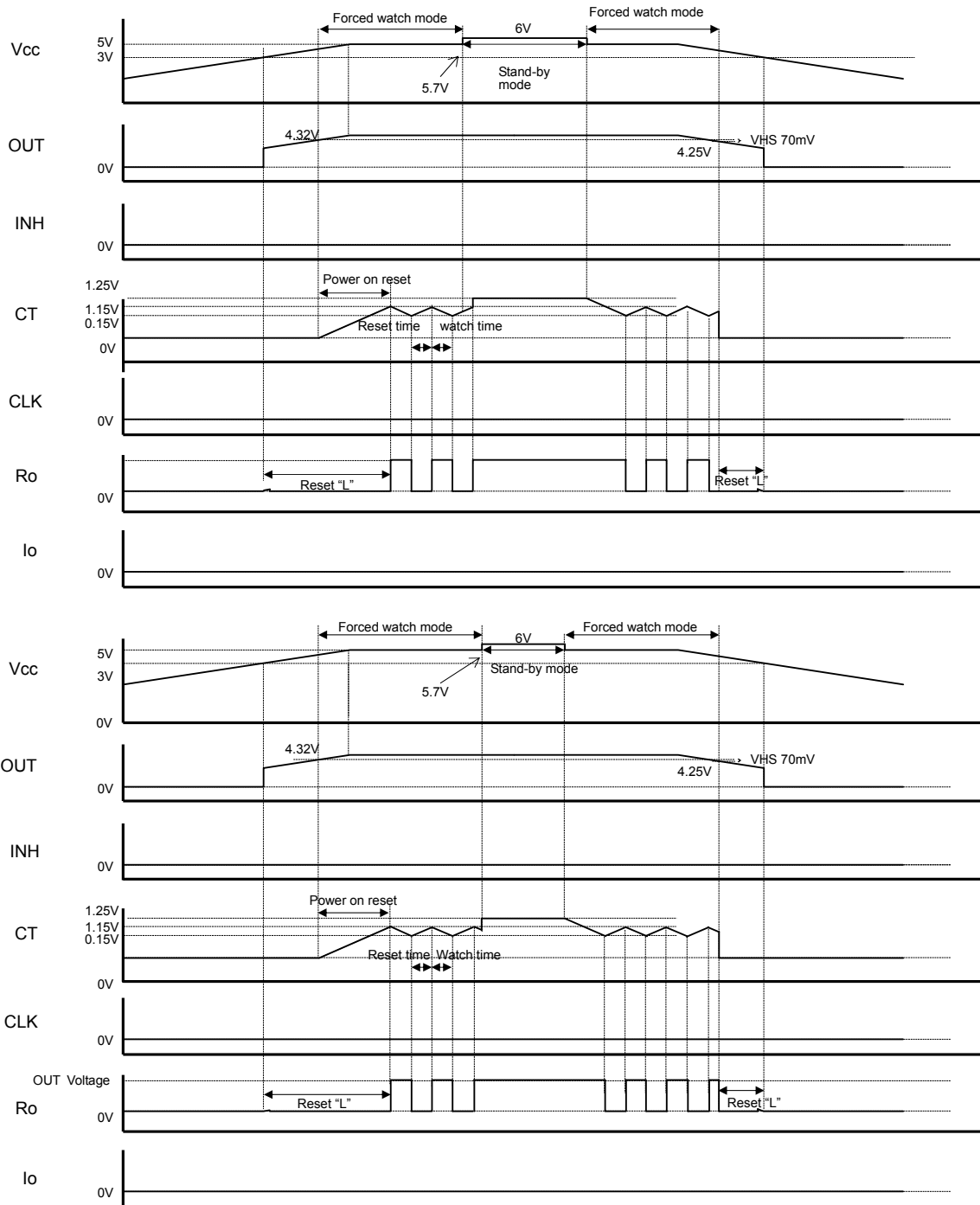
By detecting an input voltage (battery voltage) called output SAT detection, WDT can be forced to be operated.



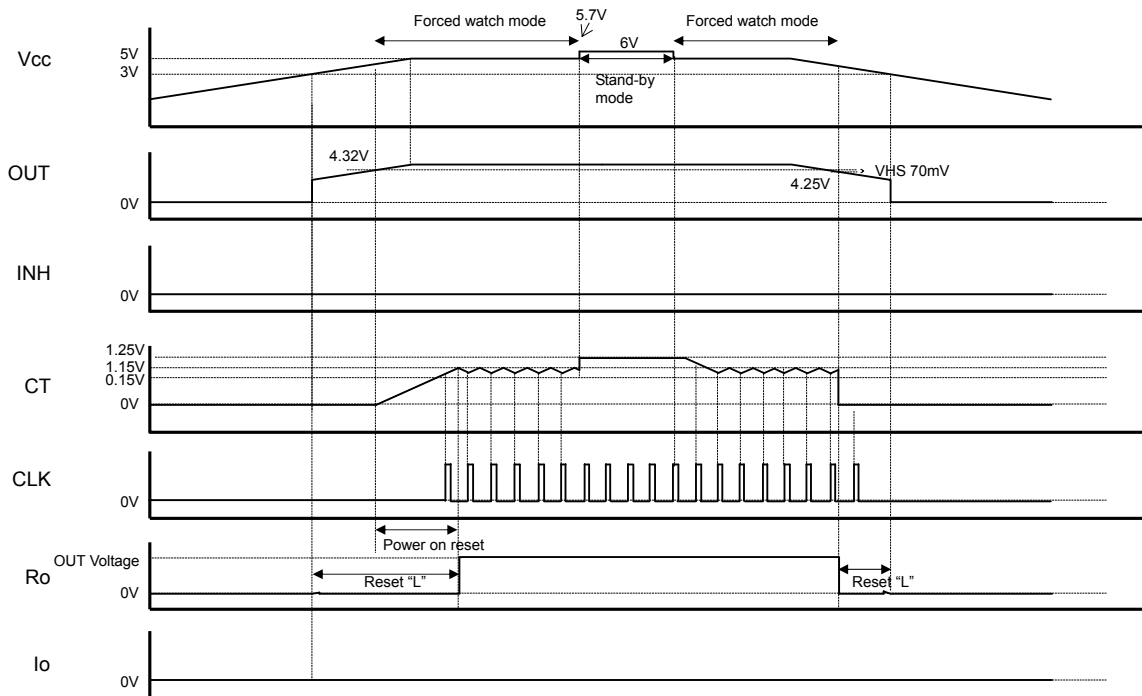
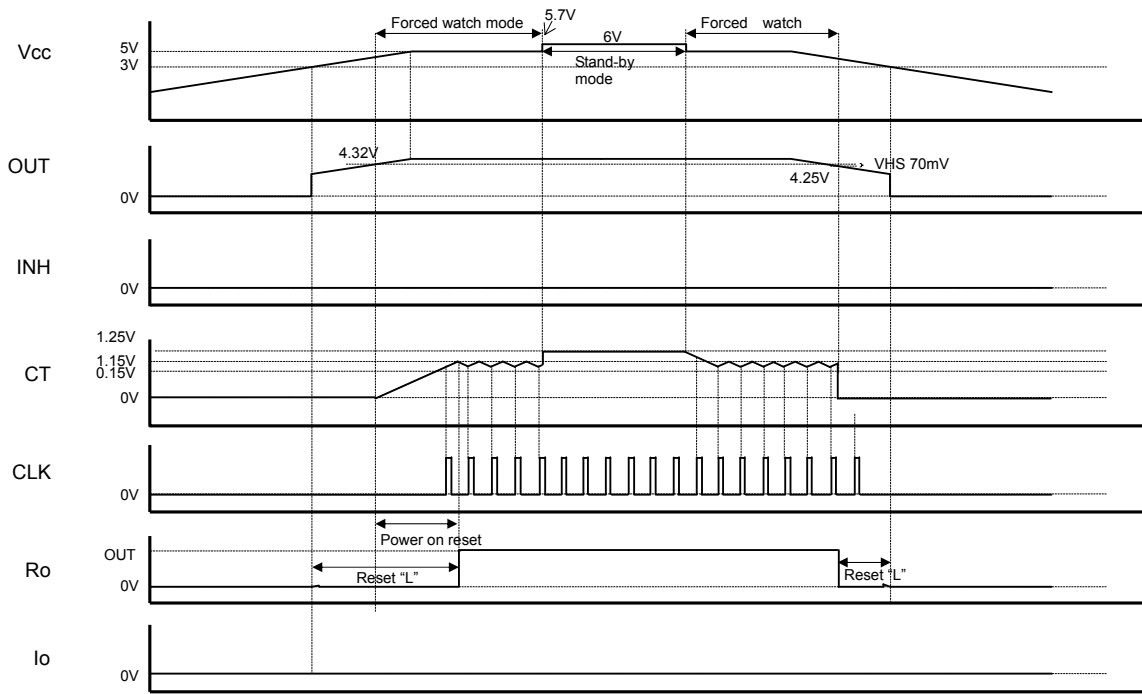
IC Internal Block Diagram

WDT will be forced ON from reset cancellation voltage to  $V_{cc} \approx 5.7V$  (WDT can be turned OFF by INH)

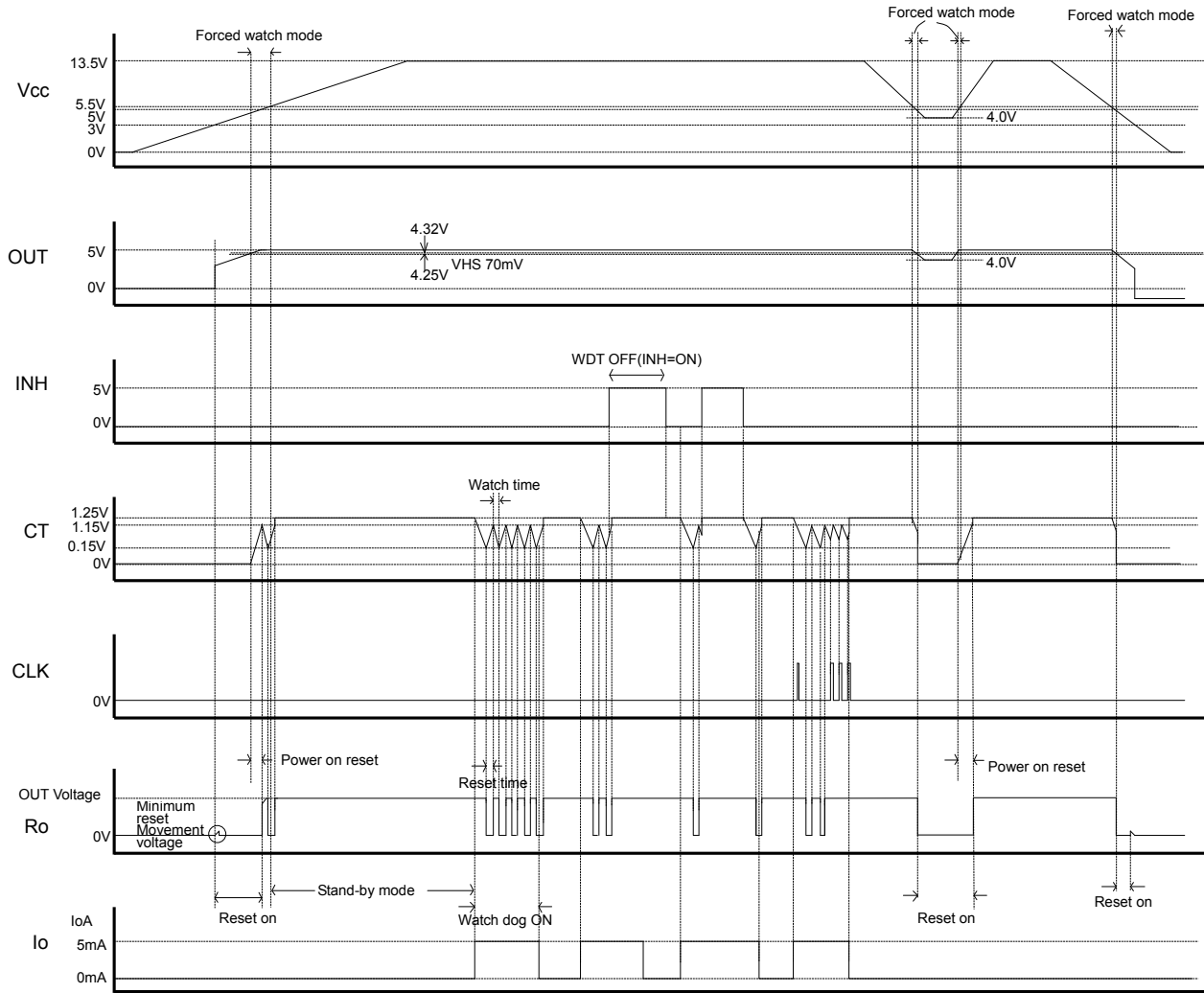
<Timing Chart including Forced Watch Mode> ※No CLK signal Input



<Timing Chart including Forced Watch Mode> ※With CLK signal Input



<Entire Timing Chart>





● Thermal Dissipation Curve

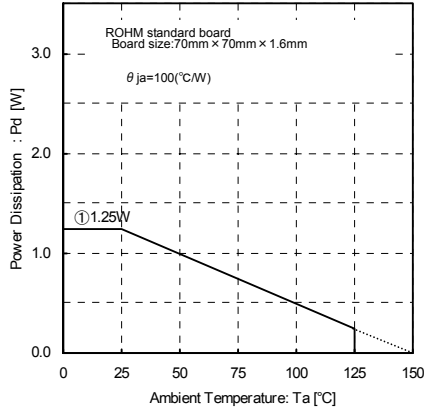


Fig. 19

※Reduced by 10.0mW/°C over Ta=25°C, when mounted on 70mm x 70mm x 1.6mm glass epoxy board

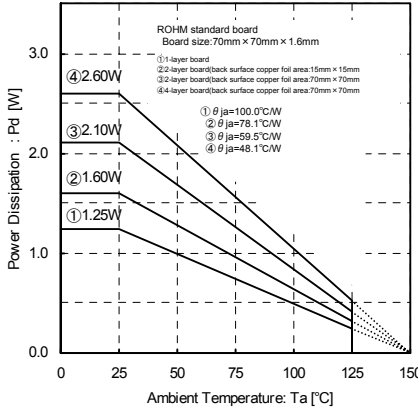


Fig.20

(Reference Data)

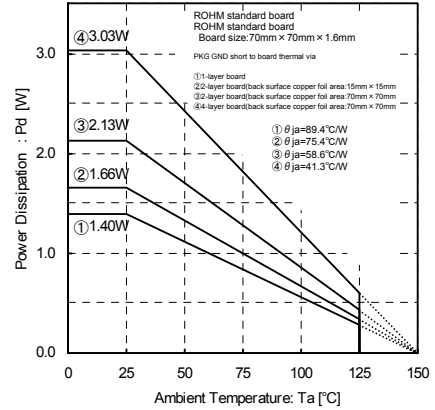


Fig.21

(Reference Data)

Refer to Fig.19 ~ 21 thermal dissipation characteristics for usage above Ta=25°C. The IC's characteristics are affected heavily by the temperature, and if it exceeds its max junction temperature (Tjmax), the chip may degrade or destruct. Thermal design is critical in terms of avoiding Instantaneous destruction and reliability in long term usage. The IC needs to be operated below its max junction temperature (Tjmax) to avoid thermal destruction. Refer to Fig. 19 ~ 21 for SSOP-B20 package thermal dissipation characteristics. Operate the IC within power dissipation (Pd) when using this IC.

Power consumption Pc(W) calculation will be as below (for Fig.21④)

$$Pc = (V_{cc} - OUT) \times I_o + V_{cc} \times I_{cc2}$$

Power dissipation  $P_d \geq Pc$

- V<sub>cc</sub> : Input Voltage
- OUT : Output Voltage
- I<sub>o</sub> : Load Current
- I<sub>cc2</sub> : Circuit Current

If load current I<sub>o</sub> is calculated to operate within power dissipation, it will be as below, where you can find the max load current I<sub>oMax</sub> for the applied voltage V<sub>cc</sub> of the thermal design.

$$I_o \leq \frac{P_d - V_{cc} \times I_{cc2}}{V_{cc} - OUT} \quad (\text{Refer to Fig2 for } I_{cc2})$$

Example) at Ta=85°C, V<sub>cc</sub>=12V, OUT=5V

$$I_o \leq \frac{1.578 - 12 \times I_{cc2}}{12 - 5} \quad \left( \begin{array}{l} \text{Fig.21④: } \theta_{ja} = 41.3^\circ\text{C/W} \rightarrow -24.2\text{mW}/^\circ\text{C} \\ 25^\circ\text{C} = 3.03\text{W} \rightarrow 85^\circ\text{C} = 1.578\text{W} \end{array} \right)$$

$$I_o \leq 200\text{mA} \quad (I_{cc2} = 110\mu\text{A})$$

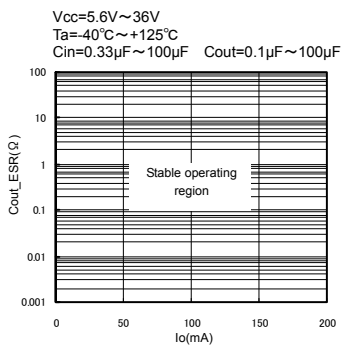
Refer to above and adjust the thermal design so it will be within power dissipation within the entire operation temperature range. Below is the power consumption Pc calculation when (OUT-GND short)

$$Pc = V_{cc} \times (I_{cc2} + I_{short}) \quad (I_{short}: \text{short current})$$

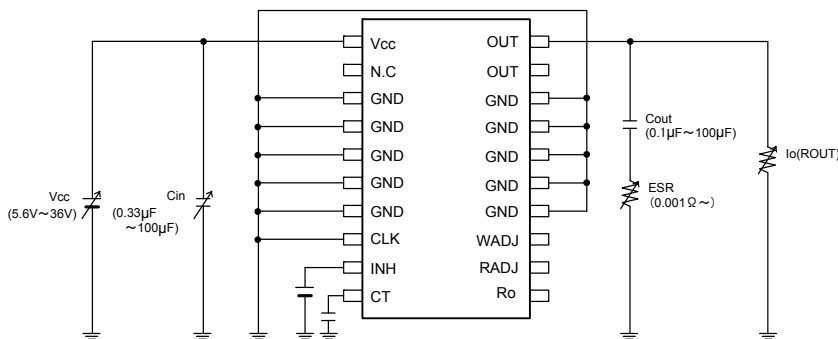
(Refer to Fig.4 for I short)

●Pin Settings / Precautions

1. Vcc pin  
Insert a 0.33 ~ 1000μF capacitor between the Vcc and GND pins. The appropriate capacitance value varies by application. Be sure to allow a sufficient margin for input voltage levels.
2. Output pins  
It is necessary to place capacitors between each output pin and GND to prevent oscillation on the output. Usable capacitance values range from 0.1μF ~ 1000μF. Abrupt fluctuations in input voltage and load conditions may affect the output voltage. Output capacitance values should be determined only through sufficient testing of the actual application.



Cout\_ESR vs Io(reference data)



※ Pin Settings / Precautions 2 Measurement circuit

3. CT pin  
Connecting a capacitance of 0.01μF ~ 1μF on the CT pin is recommended.

### ●Notes for use

#### 1. Absolute maximum ratings

Use of the IC in excess of absolute maximum ratings (such as the input voltage or operating temperature range) may result in damage to the IC. Assumptions should not be made regarding the state of the IC (e.g., short mode or open mode) when such damage is suffered. If operational values are expected to exceed the maximum ratings for the device, consider adding protective circuitry (such as fuses) to eliminate the risk of damaging the IC.

#### 2. Electrical characteristics described in these specifications may vary, depending on temperature, supply voltage, external circuits and other conditions. Therefore, be sure to check all relevant factors, including transient characteristics.

#### 3. GND potential

The potential of the GND pin must be the minimum potential in the system in all operating conditions. Ensure that no pins are at a voltage below the GND at any time, regardless of transient characteristics.

#### 4. Ground wiring pattern

When using both small-signal and large-current GND traces, the two ground traces should be routed separately but connected to a single ground potential within the application in order to avoid variations in the small-signal ground caused by large currents. Also ensure that the GND traces of external components do not cause variations on GND voltage. The power supply and ground lines must be as short and thick as possible to reduce line impedance.

#### 5. Inter-pin shorts and mounting errors

Use caution when orienting and positioning the IC for mounting on printed circuit boards. Improper mounting may result in damage to the IC. Shorts between output pins or between output pins and the power supply or GND pins (caused by poor soldering or foreign objects) may result in damage to the IC.

#### 6. Operation in strong electromagnetic fields

Using this product in strong electromagnetic fields may cause IC malfunction. Caution should be exercised in applications where strong electromagnetic fields may be present.

#### 7. Testing on application boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from a jig or fixture during the evaluation process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

#### 8. Thermal consideration

Use a thermal design that allows for a sufficient margin in light of the Pd in actual operating conditions.

Consider Pc that does not exceed Pd in actual operating conditions. ( $P_d \geq P_c$ )

Tjmax : Maximum junction temperature=150°C, Ta : Peripheral temperature[°C] ,

$$\left( \begin{array}{l} \theta_{ja} : \text{Thermal resistance of package-ambience}[^{\circ}\text{C}/\text{W}], Pd : \text{Package Power dissipation [W]}, \\ Pc : \text{Power dissipation [W]}, Vcc : \text{Input Voltage}, OUT : \text{Output Voltage}, Io : \text{Load}, Icc2 : \text{Bias Current 2} \end{array} \right)$$

$$\begin{array}{ll} \text{Package Power dissipation} & : Pd (W) = (T_{jmax} - T_a) / \theta_{ja} \\ \text{Power dissipation} & : Pc (W) = (V_{cc} - OUT) \times I_o + V_{cc} \times I_{cc2} \end{array}$$

#### 9. Output voltage clamp

To prevent rises in the output voltage in response to current surges through the load, the IC incorporates an output voltage clamp circuit. This circuit helps prevent damage to the microcontroller due to output voltage overshoot. However, this circuit is only effective for circuit paths with instantaneous peak currents and therefore does not support DC operation.

#### 10. For an infinitesimal fluctuations of output voltage.

At the use of the application that infinitesimal fluctuations of output voltage caused by some factors (e.g. disturbance noise, input voltage fluctuations, load fluctuations, etc.), please take enough measures to avoid some influence (e.g. insert the filter, etc.).

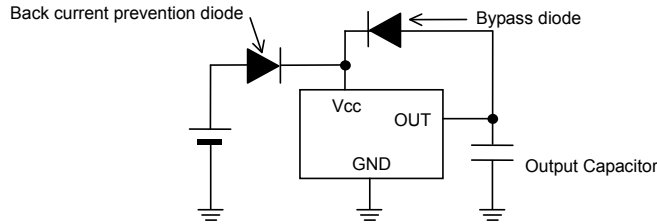
#### 11. Over current protection circuit (OCP)

The IC incorporates an integrated over-current protection circuit that operates in accordance with the rated output capacity. This circuit serves to protect the IC from damage when the load becomes shorted. It is also designed to limit output current (without latching) in the event of a large and instantaneous current flow from a large capacitor or other component. These protection circuits are effective in preventing damage due to sudden and unexpected accidents. However, the IC should not be used in applications characterized by the continuous or transitive operation of the protection circuits.

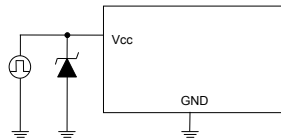
#### 12. Thermal shutdown circuit (TSD)

The IC incorporates a built-in thermal shutdown circuit, which is designed to turn the IC off completely in the event of thermal overload. It is not designed to protect the IC from damage or guarantee its operation. ICs should not be used after this function has activated, or in applications where the operation of this circuit is assumed.

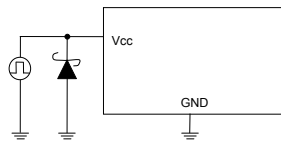
13. Applications or inspection processes where the potential of the Vcc pin or other pins may be reversed from their normal state may cause damage to the IC's internal circuitry or elements. Use an output pin capacitance of 1000µF or lower in case Vcc is shorted with the GND pin while the external capacitor is charged. Insert a diode in series with Vcc to prevent reverse current flow, or insert bypass diodes between Vcc and each pin.



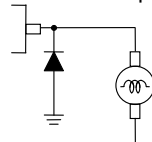
14. Positive voltage surges on VCC pin  
A power zener diode should be inserted between VCC and GND for protection against voltage surges of more than 50V on the VCC pin.



15. Negative voltage surges on VCC pin  
A schottky barrier diode should be inserted between VCC and GND for protection against voltages lower than GND on the VCC pin.



16. Output protection diode  
Loads with large inductance components may cause reverse current flow during startup or shutdown. In such cases, a protection diode should be inserted on the output to protect the IC.

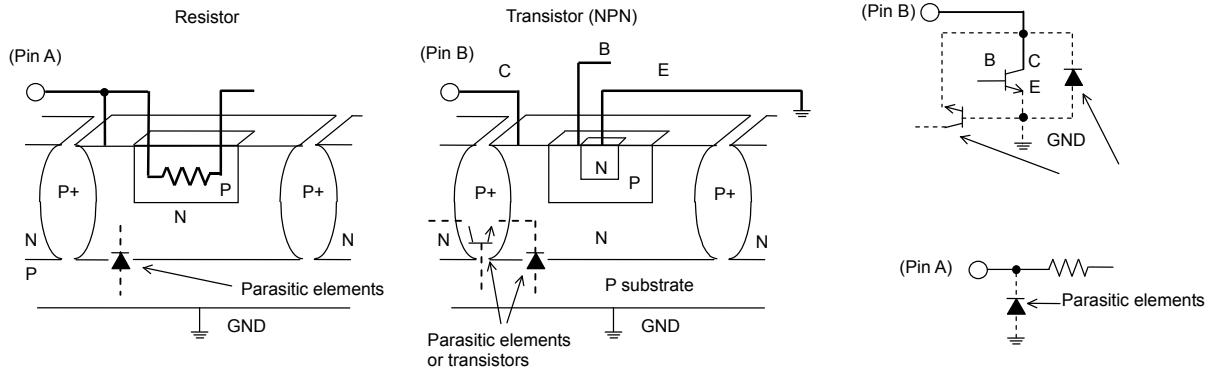


17. Regarding input pins of the IC  
This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. PN junctions are formed at the intersection of these P layers with the N layers of other elements, creating parasitic diodes and/or transistors. For example (refer to the figure below):

○When GND > Pin A and GND > Pin B, the PN junction operates as a parasitic diode

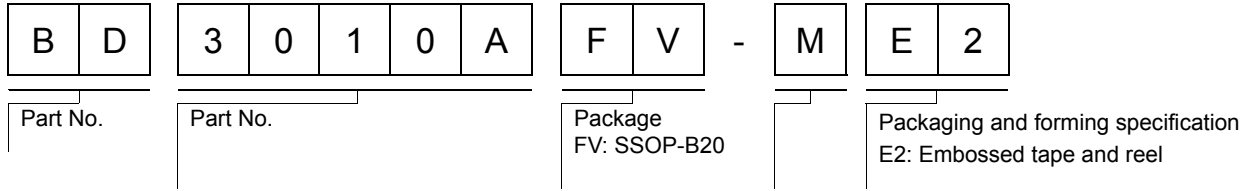
○When GND > Pin B, the PN junction operates as a parasitic transistor

Parasitic diodes occur inevitably in the structure of the IC, and the operation of these parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Accordingly, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

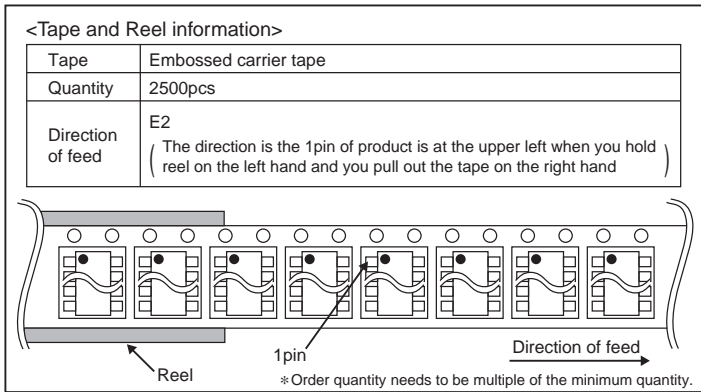
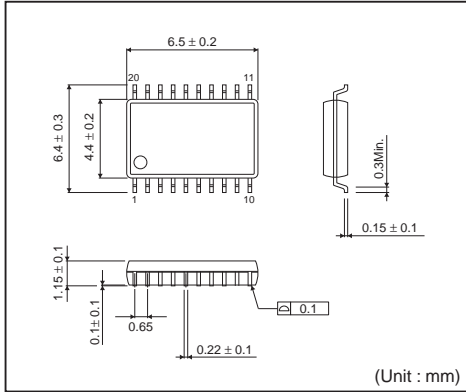


Example of Simple Monolithic IC Architecture

● Ordering part number



**SSOP-B20**



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